

Title (en)  
METHOD FOR MOULDING A FLAT ELECTRONICS MODULE ONTO THE BODY OF A PLASTIC CARD BY MEANS OF THERMOPLASTIC INJECTION MOULDING

Title (de)  
VERFAHREN ZUM EINGIESSEN EINES FLACHEN ELEKTRONIKMODULS IN EINEN KUNSTSTOFFKARTENKÖRPER DURCH THERMOPLASTISCHES SPRITZGIESSEN

Title (fr)  
PROCEDE PERMETTANT DE COULER UN MODULE ELECTRONIQUE PLAT DANS UN CORPS CARTE EN PLASTIQUE PAR MOULAGE THERMOPLASTIQUE PAR INJECTION

Publication  
**EP 1118111 A1 20010725 (DE)**

Application  
**EP 99953592 A 19990825**

Priority  
• DE 9902659 W 19990825  
• DE 19844640 A 19980929

Abstract (en)  
[origin: WO0019513A1] The module (1) is injected onto the middle of the body (2) of the plastic card, whereby the upper half (3) of the first mould (3,4) used during the first shot is shaped in such a way that the relief of the module (1) on the upper side that is to be covered and which remains initially free of injected material lies in a fully flat position on the upper half (3) of the mould without any gap therebetween, while the lower side of the module (1) is squeezed out and the lower half of the mould (6) used in the second shot lies in a flat position on the areas (7) of the body of the card that were injected during the first shot.

IPC 1-7  
**H01L 21/56**; **G06K 19/077**; **B29C 45/14**

IPC 8 full level  
**B29C 45/14** (2006.01); **B29C 45/16** (2006.01); **G06K 19/077** (2006.01); **H05K 3/28** (2006.01)

CPC (source: EP)  
**B29C 45/14647** (2013.01); **B29C 45/1671** (2013.01); **G06K 19/07745** (2013.01); **H05K 3/284** (2013.01); **H01L 2924/0002** (2013.01)

Citation (search report)  
See references of WO 0019513A1

Cited by  
EP2725149A1; WO2014064143A1

Designated contracting state (EPC)  
DE FR GB

DOCDB simple family (publication)  
**WO 0019513 A1 20000406**; EP 1118111 A1 20010725

DOCDB simple family (application)  
**DE 9902659 W 19990825**; EP 99953592 A 19990825